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DWG.NO. 04-1092A-01-FB SH 1

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M/A-COM Technology Solutions, Inc.  
PROPRIETARY AND PRIVATE

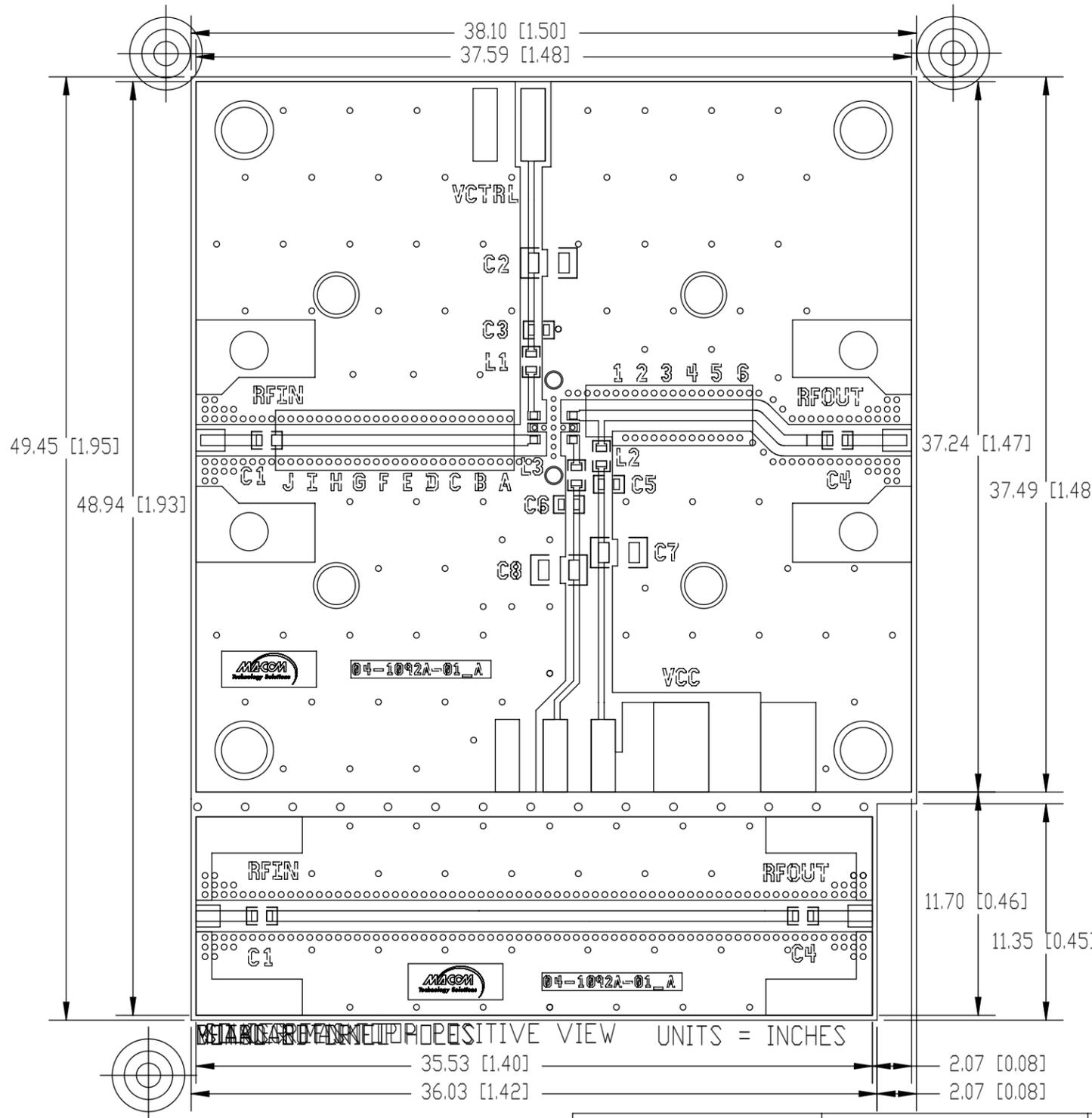
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REVISIONS

REV	DESCRIPTION	DATE	APPROVED
A	DWG INITIATED PER ECO # C-001336 HJ	26JUL11	W.H.

NOTES: (UNLESS OTHERWISE SPECIFIED)

- ONLY THE ITEM DESCRIBED ON THIS DRAWING WHEN PROCURED FROM THE VENDOR(S) LISTED HEREON IS APPROVED BY MIMIX FOR USE IN THE APPLICATION(S) SPECIFIED HEREON. A SUBSTITUTE ITEM SHALL NOT BE USED WITHOUT PRIOR APPROVAL BY MIMIX.
- IDENTIFICATION OF THE "APPROVED SOURCE(S) OF SUPPLY" HEREON IS NOT TO BE CONSTRUED AS A GUARANTEE OF PRESENT OR CONTINUED AVAILABILITY AS A SOURCE OF SUPPLY FOR THE ITEM(S) DESCRIBED ON THE DRAWING.
- DIELECTRIC MATERIAL: 0.3mm Rogers R04003C, 1oz Cu BOTH SIDES.
- HOLE SIZES DRAWN ARE DRILL SIZE - FINISHED HOLE SIZE NOT CRITICAL
- VIA PLATING 35  $\mu$ m MINIMUM
- MASK LAYERS ARE AS FOLLOWS:  
SILKSCREEN (WHITE) - LAYER SilkScreen  
TOP SOLDER RESIST BOUNDARY - LAYER SMT  
TOP METALIZATION - LAYER METAL1 (TOPSIDE SIGNAL)  
BOTTOM METALIZATION - LAYER METAL2 (BACKSIDE GROUND)  
THRU HOLE VIAS - LAYER VIAS  
SUBSTRATE ( DIELECTRIC) - LAYER SUBSTRATE
- METALISATION: GOLD PLATE OVER NICKEL.  
GOLD: PLATE PER MIL-G-45204, TYPE 3, GRADE A, CLASS 00  
PLATE 10-20 MICROINCHES MIN. ' 10%  
NICKEL: SULFAMATE NICKEL PER QQ-N-290  
PLATE 75 MICROINCHES THICK ' 10%.
- FINISH - SOLDER MASK OVER BARE COPPER, 25  $\mu$ m. SOLDER MASK WITH SR1000 OR EQUIVALENT. THE MASK MATERIAL IS COLOR GREEN.  
NO SOLDER MASK ON BOTTOM SIDE.
- THIS BOARD SHALL BE MANUFACTURED IN COMPLIANCE WITH IPC-A-600D



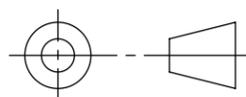
MILLIMETERS [INCHES] PROPOSITIVE VIEW UNITS = INCHES

**PRODUCTION  
RELEASE**

HOLE TABLE				
REF.	DIA.	TOL.	QTY.	PLATING
T01	2.387[0.0940]	$\pm 0.0762 [\pm 0.003]$	4	THRU
T02	0.304[0.0120]	$\pm 0.0762 [\pm 0.003]$	428	THRU
T03	0.200[0.0788]	$\pm 0.0762 [\pm 0.003]$	8	THRU
T04	0.800[0.0315]	$\pm 0.0762 [\pm 0.003]$	2	THRU
T05	0.251[0.0099]	$\pm 0.0762 [\pm 0.003]$	11	THRU
T06	0.401[0.0158]	$\pm 0.0762 [\pm 0.003]$	15	THRU
MILLIMETERS [INCHES]				

M/A SPECIFICATION S-100-101 APPLIES DO NOT SCALE THIS DRAWING

NOTE: THIS DRW INCORPORATES THIRD ANGLE PROJECTION



UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES

TOLERANCES ON

DECIMALS	ANGLES
.X $\pm .1$	$\pm 0.5^\circ$
.XX $\pm .02$	
.XXX $\pm .005$	
.XXXX $\pm$	

UNLESS OTHERWISE SPECIFIED  $\phi$  ALL OVER

MATERIAL	FINISH
X	X
NEXT ASSY	USED ON
APPLICATION	

DRAWN	DATE
W. MCKEAN	10/27/09
ENG. APP'D	
W. MCKEAN	10/27/09
Q.A. APP'D	
X	
MFG. APP'D	
X	

APPROVALS	DATE
L. PATTISON	10/27/09
JRM	01/05/10



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TITLE  
FB, PWB, R04003C, EVAL,  
SOT-363, W/TEST LINE

SIZE	CAGE CODE	DRAWING NO.
B	55NN2	04-1092A-01-FB
SCALE:	X/X	WEIGHT / SHEET 1 OF 1

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